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**IN THE CLAIMS**

1 (Previously Presented). A device comprising:

more than one spring electrical contact to contact a first side of a wafer, said first side of said wafer to have a material electrodeposited thereon; and

a base to directly support said first side of said wafer without being directly connected to said spring electrical contacts, said base to seal a second side of said wafer, said second side opposite to said first side.

2 (Original). The device of claim 1 including a soft, acid resistant material disposed on said base.

3 (Original). The device of claim 1 wherein said base is spaced inward from said contacts.

4 (Original). The device of claim 1 wherein said spring electrical contacts are connected to a frame.

5 (Original). The device of claim 4 wherein said spring electrical contacts are resilient beams that terminate with tips.

6 (Original). The device of claim 5 wherein said object has an outer edge, said base to distribute a force at said object outer edge and said tips to contact said object inward from said base.

7 (Original). The device of claim 4 wherein said base and said frame are annular.

8 (Original). The device of claim 4 wherein said frame and said beams are coated with an acid-resistant material.

9 (Previously Presented). The device of claim 1 wherein said base substantially continuously contacts said side.

10 (Previously Presented). The device of claim 1 wherein said spring electrical contacts independently deflect while electrical contact is made with said wafer.

Claims 11-30 (Canceled).